MIL-M-38510/8F <u>9 August 2005</u> SUPERSEDING MIL-M-38510/8E 4 January 2005

MILITARY SPECIFICATION

MICROCIRCUITS, DIGITAL, BIPOLAR, TTL, BUFFERS/DRIVERS OPEN COLLECTOR OUTPUT, HIGH VOLTAGE, MONOLITHIC SILICON

Inactive for new design after 7 September 1995.

This specification is approved for use by all Departments and Agencies of the Department of Defense.

The requirements for acquiring the product herein shall consist of this specification sheet and MIL-PRF 38535

- 1. SCOPE
- 1.1 <u>Scope.</u> This specification covers the detail requirements for monolithic, silicon, TTL, buffers/drivers microcircuits with open collector high voltage outputs. Two product assurance classes and a choice of case outlines and lead finishes are provided for each type and are reflected in the complete part number. For this product, the requirements of MIL-M-38510 have been superseded by MIL-PRF-38535, (see 6.4).
 - 1.2 Part or Identifying Number (PIN). The PIN is in accordance with MIL-PRF-38535, and as specified herein.
 - 1.2.1 <u>Device types.</u> The device types are as follows:

Device type	<u>Circuit</u>
01	Hex inverter buffer/driver, 30-volt output
02	Hex inverter buffer/driver, 15-volt output
03	Hex buffer/driver, 30-volt output
04	Hex buffer/driver, 15-volt output
05	Quad 2 input inverter buffer/driver 15-volt output

- 1.2.2 Device class. The device class is the product assurance level as defined in MIL-PRF-38535.
- 1.2.3 <u>Case outlines.</u> The case outlines are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Α	GDFP5-F14 or CDFP6-F14	14	Flat pack
В	GDFP4-14	14	Flat pack
С	GDIP1-T14 or CDIP2-T14	14	Dual-in-line
D	GDFP1-F14 or CDFP2-F14	14	Flat pack

Comments, suggestions, or questions on this document should be addressed to: Commander, Defense Supply Center Columbus, ATTN: DSCC-VAS, P. O. Box 3990, Columbus, OH 43218-3990, or emailed to bipolar@dscc.dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at http://assist.daps.dla.mil.

AMSC N/A FSC 5962

1.2.4 Absolute maximum ratings.

1.2.5 Recommended operating conditions.

Supply voltage (V _{CC})	4.5 V dc minimum to 5.5 V dc maximum
Minimum high level input voltage (V _{IH})	
Maximum low level input voltage (V _{IL})	0.8 V dc
Normalized fanout (each output) 3/:	
Device types 01, 02, 03, and 04	18 maximum
Device type 05	10 maximum
Case operating temperature range (T $_{\text{\tiny C}}$)	-55°C to 125°C

2.0 APPLICABLE DOCUMENTS

2.1 <u>General.</u> The documents listed in this section are specified in sections 3, 4, or 5 of this specification. This section does not include documents cited in other sections of this specification or recommended for additional information or as examples. While every effort has been made to ensure the completeness of this list, document users are cautioned that they must meet all specified requirements of documents cited in sections 3, 4, or 5 of this specification, whether or not they are listed.

2.2 Government documents.

2.2.1 <u>Specifications and standards.</u> The following specifications and standards form a part of this specification to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATIONS

MIL-PRF-38535 - Integrated Circuits (Microcircuits) Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard for Microelectronics.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines

(Copies of these documents are available online at http://assist.daps.dla.mil/quicksearch/ or http://assist.daps.dla.mil or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.3 <u>Order of precedence.</u> In the event of a conflict between the text of this specification and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

 $[\]underline{1}$ / Must withstand the added P_D due to short circuit condition (e.g. I_{OS}) at one output for 5 seconds duration.

^{2/} Maximum junction temperature should not be exceeded except in accordance with allowable short duration burn-in screening condition in accordance with MIL-PRF-38535.

^{3/} The device will fanout in both high and low levels to the specified number of inputs of the same device type as that being tested.

3. REQUIREMENTS

- 3.1 <u>Qualification</u>. Microcircuits furnished under this specification shall be products that are manufactured by a manufacturer authorized by the qualifying activity for listing on the applicable qualified manufacturers list before contract award (see 4.3 and 6.3).
- 3.2 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.
- 3.3 <u>Design, construction, and physical dimensions.</u> The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein.
- 3.3.1 <u>Logic diagram and terminal connections.</u> The logic diagram and terminal connections shall be as specified on figure 1.
 - 3.3.2 Truth tables and logic equations. The truth tables and logic equations shall be as specified on figure 2.
- 3.3.3 <u>Schematic circuits</u>. The schematic circuits shall be maintained by the manufacturer and made available to the qualifying activity and the preparing activity upon request.
 - 3.3.4 <u>Case outlines.</u> Case outlines shall be as specified in 1.2.3.
 - 3.4 Lead material and finish. Lead material and finish shall be in accordance with MIL-PRF-38535 (see 6.6).
- 3.5 <u>Electrical performance characteristics</u>. The electrical performance characteristics are as specified in table 1 and apply over the full recommended case operating temperature range, unless otherwise specified.
- 3.6 <u>Electrical test requirements.</u> The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.
 - 3.7 Marking. Marking shall be in accordance with MIL-PRF-38535.
- 3.8 <u>Microcircuit group assignment.</u> The devices covered by this specification shall be in microcircuit group number 2 (see MIL-PRF-38535, appendix A).

4. VERIFICATION

- 4.1 <u>Sampling and inspection.</u> Sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not effect the form, fit, or function as described herein.
 - 4.2 Qualification inspection. Qualification inspection shall be in accordance with MIL-PRF-38535.
- 4.2 <u>Screening.</u> Screening shall be in accordance with MIL-PRF-38535 and shall be conducted on all devices prior to qualification and conformance inspection. The following additional criteria shall apply:
 - a. The burn-in test duration, test condition, and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document control by the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II, except interim electrical parameters test prior to burn-in is optional at the discretion of the manufacturer.
 - c. Additional screening for space level product shall be as specified in MIL-PRF-38535.

TABLE I. <u>Electrical performance characteristics</u>.

		Conditions	Device		Limits	
Test	Symbol	-55°C ≤ T _C ≤ +125°C	type	Min	Max	Unit
		unless otherwise specified				
High-level output voltage	V _{OH}	1/	01, 03	30		V
			02, 04, 05	15		
Input clamp voltage	V _{IC}	V _{CC} = 4.5 V, I _{IN} = -12 mA,	All		-1.5	V
		T _A = 25° C				
Maximum collector	I _{CEX}	V _{CC} = 4.5 V,	All		250	μΑ
cut-off current		$V_{OH} = MAX \underline{4}/$				
Low-level output voltage	V _{OL1}	V _{CC} = 4.5 V, I _{OL} = 30 mA,	01, 02		0.7	V
		<u>4</u> /	03, 04			
Low-level output voltage	V _{OL2}	$\frac{4}{\text{V}_{CC}} = 4.5 \text{ V}, I_{OL} = 16 \text{ mA},$	All		0.4	V
		<u>4</u> /				
High-level input current	I _{IH1}	$V_{CC} = 5.5 \text{ V}, V_{IN} = 2.4 \text{ V} \underline{2}/$	All		40	μА
High-level input current	I _{IH2}	V _{CC} = 5.5 V, V _{IN} = 5.5 V <u>2</u> /	All		100	μА
Low-level input current	I _{IL1}	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0.4 \text{ V}$ 3/	01, 02	-0.4	-1.6	mA
			03, 04			
			05	-0.7	-1.6	
High-level supply current	I _{CCH}	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V}$	01, 02		51	mA
		$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}$	03, 04		46	mA
		$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V}$	05		8	mA
Low-level supply current	I _{CCL}	$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}$	01, 02		48	mA
		$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V}$	03, 04		32	mA
		$V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}$	05		22	mA
Propagation delay time	t _{PHL}	C_L = 50 pF ±10% minimum,	01, 02	3	30	ns
high-to-low level		$R_L = 150 \Omega \pm 5\%$	03, 04	3	35	ns
		C_L = 50 pF ±10% minimum,	05	3	35	ns
		$R_L = 1 \text{ k}\Omega \pm 5\%$				
Propagation delay time	t _{PLH}	C_L = 50 pF ±10% minimum,	01, 02	3	25	ns
low-to-high level		$R_L = 150 \Omega \pm 5\%$	03, 04	3	20	ns
		$C_L = 50 \text{ pF} \pm 10\% \text{ minimum},$	05	3	40	ns
		$R_L = 1 \text{ k}\Omega \pm 5\%$				

 ^{1/} See I_{CEX}.
2/ All unspecified inputs grounded.
3/ All unspecified input at 5.5 volts.
4/ V_{IL} = 0.7 V at 125°C only as follows:
 I_{CEX}: device types 01, 02, 05.
 V_{OL1}, V_{OL2}: device types 03 and 04.

TABLE II. Electrical test requirements.

	Subgroups (see table III)
MIL-PRF-38535 Test requirement	Class S Devices	Class B Devices
Interim electrical parameters	1	1
Final electrical test parameters	1*, 2, 3, 9, 10, 11	1*, 2, 3, 9
Group A test requirements	1, 2, 3, 9, 10, 11	1, 2, 3 9, 10, 11
Group B electrical test parameters when using the method 5005 QCI option	1, 2, 3, 9, 10, 11	N/A
Groups C end point electrical parameters	1, 2, 3 9, 10, 11	1, 2, 3
Group D end point electrical parameters	1, 2, 3	1, 2, 3

^{*}PDA applies to subgroup 1.

- 4.3 Qualification inspection. Qualification inspection shall be in accordance with MIL-PRF-38535.
- 4.4 <u>Technology Conformance Inspection (TCI).</u> Technology conformance inspection shall be in accordance with MIL-PRF-38535 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).
- 4.4.1 <u>Group A inspection.</u> Group A inspection shall be in accordance with table III of MIL-PRF-38535 and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, 6, 7, and 8 shall be omitted.
 - 4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of MIL-PRF-38535.
- 4.4.3 <u>Group C inspection.</u> Group C inspection shall be in accordance with table IV of MIL-PRF-38535 and as follows:
 - a. End point electrical parameters shall be as specified in table II herein.
 - b. The steady-state life test duration, test condition, and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document control by the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
- 4.4.4 Group D inspection. Group D inspection shall be in accordance with table V of MIL-PRF-38535. End-point electrical parameters shall be as specified in table II herein.
 - 4.5 Methods inspection. Methods of inspection shall be as specified in the appropriate tables and as follows:
- 4.5.1 <u>Voltage and current</u>. All voltages given are referenced to the microcircuit ground terminal. Currents given are conventional current and positive when flowing into the referenced terminal.

DEVICE TYPES 01 AND 02

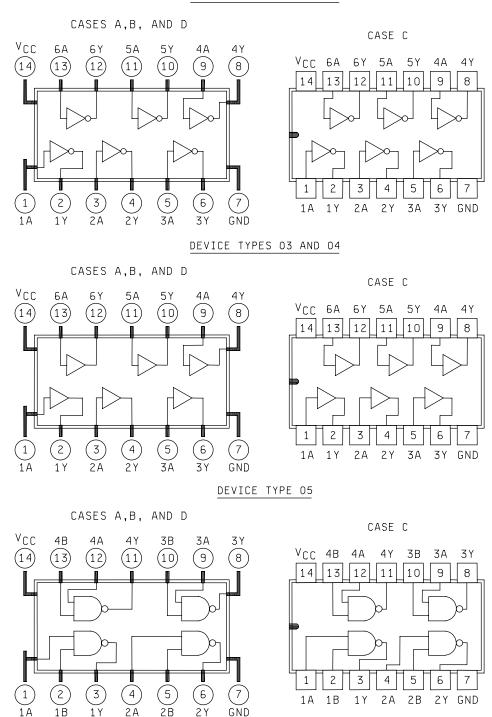


Figure 1. Logic diagram and terminal connections (top views).

Device types 01 and 02

Truth table	each gate
Input	Output
А	Y
L	Н
Н	L

Positive logic Y = \overline{A}

Device type 03 and 04

Truth table	each gate
Input	Output
Α	Υ
L	L
Н	Н

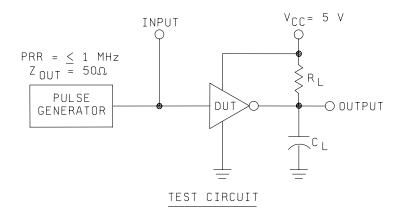
Positive logic Y = A

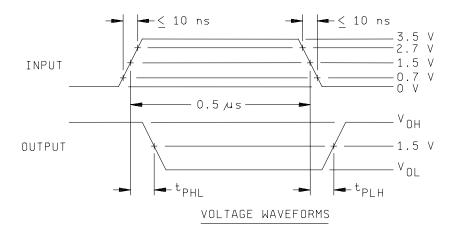
Device type 05

	71	
Tr	uth table ead	ch gate
In	put	Output
Α	В	Y
L	L	Н
Н	L	Н
L	Н	Н
Н	Н	L

Positive logic Y = \overline{AB}

Figure 2. Truth tables and logic equations.

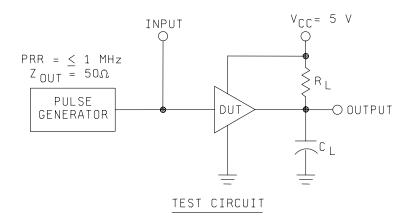


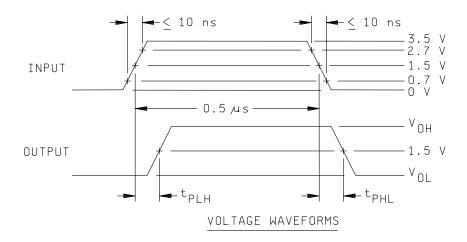


NOTES:

- 1. C_L = 50 pF \pm 10% minimum including scope probe, wiring, and stray capacitance, without package in test fixture
- 2. Voltage measurements are to be made with respect to network ground terminal.
- 3. $R_L = 150 \Omega \pm 5\%$.

FIGURE 3. Switching time test circuit for device types 01 and 02.

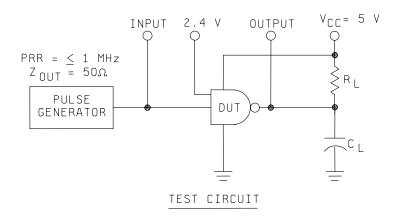


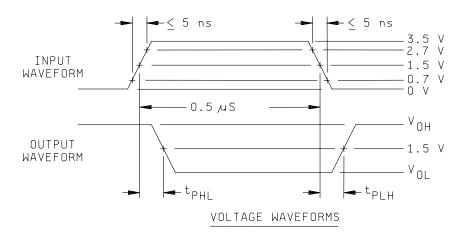


NOTES:

- 1. C_L = 50 pF \pm 10% minimum including scope probe, wiring, and stray capacitance, without package in test fixture.
- 2. Voltage measurements are to be made with respect to network ground terminal.
- 3. $R_L = 150 \Omega \pm 5\%$.

FIGURE 4. Switching time test circuit for device types 03 and 04.





NOTES:

- 1. C_L = 50 pF \pm 10% minimum including scope probe, wiring, and stray capacitance, without package in test fixture.
- 2. Voltage measurements are to be made with respect to network ground terminal.
- 3. $R_L = 1 k\Omega \pm 5\%$.

FIGURE 5. Switching time test circuits for device type 05.

TABLE III. Group A inspection for device type 01 and 02. Terminal conditions (High ≥ 2.0 V or Low ≤ 0.8 V or open).

																																						\neg
its	: -		>	n	n	"	3	n	n	"	n	"	3	3	μ	n	n	n	=	3	>	3	"	3	ä	79	Ą	=	3	"	n	я	=	-	7	я	я	n
Test limits	Max	N N	0.7	77	3	3	3	3	0.4	3	=	=	=	=	250	n	"	"	=	n	-1.5	3	=	3	3	31	40	=	3	3	3	3	100	-	3	3	3	3
Ĭ	Δi																																					
	Meas.	2	17	27	37	74	5Υ	Α9	17	27	37	4≺	5Υ	Α9	17	27	37	4≺	57	Α9	14	2A	3A	44	2A	6A	1A	2A	3A	44 4	2A	6A	14	2A	3A	44	2A	6A
41	14	Vcc	4.5 V	=	=	=	=			=	=	=	=	=		=	=	=	=		=	=	=	=	-	=	5.5 V	=	=	=	=	=	=	=	=	=	=	
13	13	6A	5.5 V	=	=	=		2.0 V	5.5 V	=	=			2.0 V	5.5 V	-				0.8 V						-12 mA		-	-	=		2.4 V	GND			=		5.5 V
12	12	К9						30 mA		=				16 mA		-				∢		=							GND									
7	11	5A	5.5 V				2.0 V	5.5 V					2.0 V	5.5 V					0.8 V	5.5 V					-12 mA		GND				2.4 V	GND					5.5 V	GND
10	10	5Y					30 mA	=	=			-	16 mA	-	-			-	₹		=										=	-	=			=	-	-
6	6	44	5.5 V	=		2.0 V	5.5 V			=			5.5 V		=			0.8 V	5.5 V	5.5 V				-12 mA				=		2.4 \	GND		=		-	5.5 V	GND	GND
8	8	47				30 mA						16 mA						∢											GND									
7	7	GND	GND				-	-	=					-	=					-	=	-	=		-	=	-			=		-	=			-	-	=
9	9	37			30 mA		-		=		16 mA						⋖				=											-						=
2	5	3A	5.5 V	5.5 V		5.5 V	=			-		5.5 V	-			-	0.8 V	5.5 V	=				-12 mA				GND	GND	2.4 V	GND	-		-		5.5 V	GND	-	-
4	4	2Y		30 mA						16 mA						⋖																					-	
က	3	2A	5.5 V	2.0 V	5.5 V	-	=	=		2.0 V	5.5 V					0.8 V	5.5 V			=		-12 mA						2.4 V	GND	-			=	5.5 V	GND	=	=	=
2	2	1	30 mA						16 mA						A														GND									
_	1	14	2.0 V	5.5 V	-	=	=			5.5 V	-	=	-	-	0.8 V	5.5 V	=	=	-		-12 mA						2.4 V	GND	=	=	=	-	5.5 V	GND	-	=	=	=
Cases A,B,D	Case C	Test No.	1	7	က	4	2	9	7	∞	o	10		12	13	4	15	16	17	18		20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36
	MIL- STD-883	method	3007	3	я	3	3	я	n	3	=	я	3	я													3010	я	-			=	3010	3	=	=	=	=
	OdmyS	9	Vol1	ı	"	n	3	n	Vol2	71	-	3	71	"	ICEX	n	3	3	-	"	VIC	3	3	7	3	n	<u>H</u>		n	3	n	"	I _{IH2}		3	7	7	ä
	o loroding	200	1	$T_{C} = +25^{\circ}C$	3	3	3	2	3	3,6	ä	3	3	z	3	з	я	3	3	3	3	я	и	я	n	3	3	3	3	и	3	z	3	3	3	n	n	a

Note: A = 30 volts for device type 01 and 15 volts for device type 02.

TABLE III. Group A inspection for device type 01 and 02. - Continued Terminal conditions (High \geq 2.0 V or Low \leq 0.8 V or open).

ts	ţici	0	mA	n	n	"	71	71	"	"	71	71	=	n	n	"	n		-	"			ns	"	,,	,,	"	"	=	"	ä	n	n	n
Test limits	M	MICA	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	41	48	44	42	51	48			25	n	n	n	n	n	20	"	n	"	"	"
ĭ	Min		7:-	4	7:-	4	7	4	7	4	7	4	7	4									3	-		-	-			-	-	=	-	=
	Meas.		14	1A	2A	2A	3A	3A	44	4 A	2A	2A	6A	6A	V _{CC}	=	=	=	=				1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	5A to 5Y	6A to 6Y	1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	5A to 5Y	6A to 6Y
14	41	$^{\circ\circ}\Lambda$	2.5 V	=	=	=	=	=	=	=	=	=	=	=	=	=	=	=	=	=			5.0 V	=	=	=	=	=	=	=	=	=	=	=
13	13	6A	5.5 V				=	=	-	=			0.4 V	0.4 V	5.5 V	=	=			=								Z						Z
12	12	К9												=	=					GND								OUT						OUT
11	11	5A	5.5 V								0.4 V	0.4 V	5.5 V					GND									Z						Z	
10	10	λ9					=	=	=	=	=	=	=				=	=	=	=	or ICEX.	=					OUT						OUT	
9	9	4A	5.5 V			=	=	=	0.4 V	0.4 V	5.5 V	=	=			=				"	= 0.7 V f					Z						Z		
8	8	47																		GND	itted. V _{IL}	ted.				OUT						OUT		
7	7	GND	GND		=	=				=	=	=	=	=	=	=	=	=	=		its are om	s are omi	GND		=	=	=	=	=	=	=	=	=	=
9	9	3Y									-	-									nd V _{IC} tes	d V _{IC} test			DUT						DUT			
5	5	3A	5.5 V				0.4 V	0.4 V	5.5 V	-	-	-	-	-	=	-	-	GND	-		125° C ar	55° C an			Z						Z			
4	4	2Y					-	-	-												ept T _C =	p 1, except $T_C = -55^{\circ} C$ and V_{IC} tests are omitted.		OUT						OUT				
3	3	2A	5.5 V	5.5 V	0.4 V	0.4 V	5.5 V	=	-	=	=	=	=	=	=	-	-		=		up 1, exc	up 1, exc		z						Z				
2	2	17																		GND	for subgro	for subgro	OUT						OUT					
1	1	1A	0.4 V	0.4 V	5.5 V	-	=	=	-	=	=	=	=	-	=	=	-	GND	-		l limits as	limits as	Z						Z					
Cases A,B,D	Case C	Test No.	37 CKT A, C	37 CKT B	38 CKT A, C	38 CKT B	39 CKT A, C	39 CKT B	40 CKT A, C	40 CKT B	41 CKT A, C	41 CKT B	42 CKT A, C	42 CKT B	43 CKT A	43 CKT B	43 CKT C	44 CKT A	44 CKT B	44 CKT C	Same tests, terminal conditions and limits as for subgroup 1, except $T_C = 125^{\circ}$ C and V_{IC} tests are omitted. $V_{IL} = 0.7$ V for I_{CEX}	Same tests, terminal conditions and limits as for subgroul	45	46	47	48	49	20	51	52	53	54	55	99
	MIL- STD-883	method	3009	3	"	3	77	77	3	77	77	77	77	3	3005	"	ä	=	-		sts, termina	sts, termina	3003	(Fig 3)	-	=	=	-	=	-	-	-	-	-
	lodmyS		II.	я	3	я	з	з		з	з	з	3	я	ICCL	3	я	Іссн	-		Same te	Same tes	tPHL	я	я	я	*	я	tPLH	я	я	3	3	3
	Cliporoding	doolean	-	$T_{\rm C} = +25^{\circ}{\rm C}$	3	3	3	3	3	31	31	я	3	3	3	"	3	3	3	и	2	က	6	$T_{\rm C} = +25^{\circ}{\rm C}$	3	я	3	3	=	=	3	я	я	я

TABLE III. Group A inspection for device type 01 and 02. - Continued Terminal conditions (High \geq 2.0 V or Low \leq 0.8 V or open).

			Cases A,B,D	_	2	3	4	2	9	7	80	6	10	11	12	13	14		Te	Test limits	6
Subgroup	Odmyo	MIL- Symbol STD-883	Case C	1	2	3	4	5	9	7	8	6	10	11	12	13	14	Meas.	Min	Λον	: <u>:</u>
2000	O)	method	Test No.	14	17	2A	2Y	3A	37	GND	44	4A	5Y	5A	Д9	6A	V _{cc}	<u> </u>			<u> </u>
10	THd	3003	25	N	OUT					GND							5.0 V	1A to 1Y	3	30	us
T _C = +125°C	3	(Fig 3)	58			Z	OUT							_			=	2A to 2Y	-	я	ä
3	3	=	59					Z	TUO								=	3A to 3Y		я	ä
3	3	=	09								DOT	Z					=	4A to 4Y		я	ä
3	3	=	61										OUT	Z			=	5A to 5Y		я	ä
3	3	=	62												OUT	Z	=	6A to 6Y	=	з	з
=	нПd	=	63	N	OUT													1A to 1Y	=	25	=
-	3	=	2			Z	OUT			-							=	2A to 2Y		n	ä
3	3	=	65					Z	TUO	-							=	3A to 3Y		n	ä
3	3	=	99							-	DOUT	Z					=	4A to 4Y		я	ä
2	3	=	29										OUT	Z			=	5A to 5Y	=	з	3
п	п		68							"					OUT	Z		6A to 6Y	=	п	n
11	Same te	sts, termina	Same tests, terminal conditions and limits as for subgroup 10, except $T_{\rm C}$ = -55° C.	l limits as	for subare	oup 10, e	xcept Tc =	: -55°C.													

TABLE III. Group A inspection for device type 03 and 04. Terminal conditions (High ≥ 2.0 V or Low ≤ 0.8 V or open).

																					1													_		_	_	\neg
iits	<u> </u>		>	"	3	3	"	ä	"	3	n	3	3	n	η				=	3	>	7	"	3	3	n	Μ	=	3	3	7	3	=	=	7	ä	3	ä
Test limits	M	N N	0.7	"	3	n	3	3	0.4	3	-	=	=	-	250	31	31	31	=	"	-1.5	n	n	"	3	n	40	=	"	31	n	"	100	=	n	3	3	ä
-	Σi	2																																				
	Meas.	<u> </u>	1	27	37	4∀	57		17	27	37	4∀	57		1	27	37	4≺	2λ		1A	2A	3A	44	2A	6A	14	2A	3A	4 A	5A	6A	14	2A	3A	44	5A	6A
41	14	Vcc	4.5 V	=		=	=	-	=	=	=	=	=	=	=	=	=	=	=	=	=	=	=	=	=		5.5 V	=	=	=	=	=	=	=	=	=	=	=
13	13	6A	5.5 V	=		=		0.8 V	5.5 V	=	=	=		0.8 V	5.5 V	=	=	=		2.0 V						-12 mA		=	=	=		2.4 V	GND	=	=	=		5.5 V
12	12	К9						30 mA		=				16 mA		-				∢		-							GND					-				
11	11	5A	5.5 V				0.8 V	5.5 V					0.8 V	5.5 V					2.0 V	5.5 V					-12 mA		GND				2.4 V	GND					5.5 V	GND
10	10	5Y					30 mA	-	=			-	16 mA	-	=			-	₹		=										=	-	=			=	-	
6	6	44	5.5 V	-	-	0.8 V	5.5 V	-	=			0.8 V			=			2.0 V	5.5 V	5.5 V				-12 mA						2.4 V	GND	=	=	-	-	5.5 V	GND	GND
8	8	4				30 mA						16 mA						∢											GND									
7	7	GND	GND		=		=	=	=	=	=		=	=	=					=	=	=	=	=	=		=	=		-	=	=	=	=		=	=	=
9	9	37			30 mA		-		=		16 mA				=		⋖				=											-						=
2	2	3A	5.5 V	5.5 V	0.8 V	5.5 V	-	=			0.8 V	5.5 V	=		=		2.0 V	5.5 V		=			-12 mA				GND	GND	2.4 V	GND			=		5.5 V	GND		=
4	4	27		30 mA						16 mA						∢																						
3	က	2A	5.5 V	0.8 V	5.5 V	-	-	=	=	0.8 V	5.5 V	-	-		=	2.0 V	5.5 V	-	-	-		-12 mA						2.4 V	GND	-	-		=	5.5 V	GND	=		=
2	2	7	30 mA						16 mA						∢														GND									
~	-	1A	0.8 V	5.5 V		=	=	=	0.8 V	5.5 V	=	=	=		2.0 V	5.5 V	=	=	=	=	-12 mA						2.4 V	GND	=	=	=	=	5.5 V	GND	=	=	=	:
Cases A,B,D	Case C	Test No.	-	2	က	4	2	9	7	80	6	10	1	12	13	41	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36
	MIL- STD-883	method	3007	"	n	n	77	n	n	n	=	n	n	n													3010	n	=	=	=	=	3010	n	=	=	=	=
	odanyo		Vol1	3	я	3	3	я	Vol2	n	-	я	я	я	ICEX	, ,	ä	3	=	3	VIC	я	я	я	3	и	I _{IH1}		n	71	я	n	I _{IH2}		я	я	3	3
	O. Daily	dno ificano	-	T _C = +25°C	я	я	3	E.	z	3.6	я	"	"	3	3	3	n	n	3	n	n	3	z	z	n	ı	3	п	п	и	7	п	3	2	7	3	z	я

Note: A = 30 volts for device type 03 and 15 for device type 04.

-X-

TABLE III. Group A inspection for device type 03 and 04. - Continued Terminal conditions (High ≥ 2.0 V or Low ≤ 0.8 V or open).

(2	±		МA	n	3	n	3	3	n	n	я	n n		3	n	3	-	-			ns	3	ä	×	ņ	×	-	"	'n	ä	×	3
Test limits	Max	5	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	-1.6	-1.3	42	46	30	32			26	3	3	3	n	n	15	3	3	3	3	3
Te	Αi		7:-	4.						4.			7:-								3	-	=	-	=		-	=	=	=	-	-
	Meas.	5	14	14	2A	2A	3A	3A	44	44	2A	2A	6A	6A	Vcc	=	=	=			1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	5A to 5Y	6A to 6Y	1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	5A to 5Y	6A to 6Y
14	14	V_{CC}	5.5 V	-	=	-	-	=	-	-	-	-	-	-	=		=				5.0 V		=							=		
13	13	99	2.5 V	-	=	=	-	=	-	=			0.4 V	0.4 V	5.5 V	5.5 V										Z						Z
12	12	6У													=				GND	•						OUT						OUT
11	11	5A	5.5 V								0.4 V	0.4 V	5.5 V				GND	GND	id Vol2.						Z						Z	
10	10	5Y					-				-	-	-					= :	r Voli an						DUT						DUT	
6	6	4A	5.5 V	=	=	=	=	=	0.4 V	0.4 \	5.5 V		=	-	=	=	GND		= 0.7 V fc					Z						Z		
8	8	47																	tted. VIL	ed.				DUT						OUT		
7	7	GND	GND	-	=	-				-	-	-	-	-	=		=		125° C and Vi _C tests are omitted. $V_{LL} = 0.7 \text{ V}$ for V _{OL1} and V _{OL2} .	s are omit	GND		=				=			=		-
9	9	3Y								-	-	-							id V _{IC} test	V _{IC} tests			TUO						TUO			
2	5	3A	5.5 V				0.4 \	0.4 V	5.5 V		-	-	-	-	=	=	GND	GND	125° C ar	55° C and			Z						z			
4	4	2Y					=	=	=										ept T _C =	ept T _C = -		DOUT						DUT				
3	3	2A				0.4 V		-		-		-		-	=				up 1, exc	up 1, exc		Z						Z				
2	2	17																	or saying	or subgro	OUT						OUT					
-	1	1A	0.4 V	0.4 V	5.5 V	=	=	=	=	=	-	-	-	-	=	=	GND	GND	limits as 1	limits as 1	Z						Z					
Cases A,B,D	Case C	Test No.	37 CKT A, C	37 CKT B	38 CKT A, C	38 CKT B	39 CKT A, C	39 CKT B	40 CKT A, C	40 CKT B	41 CKT A, C	41 CKT B	42 CKT A, C	42 CKT B	43 CKT A, B	43 CKT C	44 CKT A, B	44 CKT C	Same tests, terminal conditions and limits as for subgroup 1, except $T_{\rm C}$ =	Same tests, terminal conditions and limits as for subgroup 1, except $T_C = -55^{\circ}$ C and V_{IC} tests are omitted	45	46	47	48	49	20	51	52	53	54	55	26
	MIL- STD-883	method	3009	3	3	3	3	3	3	3	3	3	3	3	3005	3	=	-	ts, termina	ts, termina	3003	(Fig 4)	=	-	=	-	=			-		-
	lodmyS		11	3	n	3	3	¥	-	3	3	n	3	3	lccL	ICCL	ГССН	ICCH	Same tes	Same tes	tpHI	3	¥	3	3	3	tP∟H	n	3	ä	ņ	3
	o o o o		1	$T_C = +25^{\circ}C$	я	79	79	7	79	79	n	n	n	n	3	я	3	3	2	က	6	T _C = +25°C	3	3	3	3	=		n	я	я	77

TABLE III. Group A inspection for device type 03 and 04. - Continued Terminal conditions (High ≥ 2.0 V or Low ≤ 0.8 V or open).

			Cases A,B,D	_	2	3	4	2	9	7	80	6	10	11	12	13	14		Te	Test limits	
Subgroup	Odmyo	MIL- STD-883	Case C	-	2	3	4	5	9	7	8	6	10	11	12	13	14	Meas.	Min	Min Max	±
dnoibano	Syllipol	method	Test No.	14	1	2A	2Y	3A	37	GND	47	4A	5Y	5A	К9	6A	Vcc	מ	_	N N	
10	tPHL	3003	22	Z	OUT					GND							5.0 V	1A to 1Y	3	35	ns
$T_{\rm C} = +125^{\circ}{\rm C}$	3	(Fig 4)	58	_		Z	OUT			-				_			-	2A to 2Y		з	я
71	3	=	59					Z	TUO	-				_			-	3A to 3Y		ä	ä
71	3	=	09							-	OUT	Z		_			-	4A to 4Y		ä	ä
71	3	=	61							-			OUT	Z			-	5A to 5Y		ä	ä
n	3	=	62	_											TUO	Z		6A to 6Y	=	з	'n
	фГН	=	63	Z	OUT												=	1A to 1Y	=	20	=
	2	=	64			Z	OUT			-				_			-	2A to 2Y		n	3
n	3	=	65					Z	TUO	-				_			-	3A to 3Y		n	3
n	3	=	99							-	OUT	Z		_			-	4A to 4Y		я	3
n	3	=	29							-			OUT	Z			-	5A to 5Y		я	3
n	n	=	68												OUT	Z	-	6A to 6Y		п	п
11	Same te	sts, termina	Same tests, terminal conditions and limits as for subgroup 10, except T_C = -55°C.	limits as	for subgr	oup 10, e:	xcept Tc =	= -55°C.													

TABLE III. Group A inspection for device type 05. Terminal conditions (High ≥ 2.0 V or Low ≤ 0.8 V or open).

	±.		>	n	ņ	3	μĄ	3	n	3	n	ä	3	3	>	3	3	"	-	n		3	¥	3	3	"	-	-	3	3	n	3	-	-	3	3	3	3	
Test limits	> o M		9.0	3	3	з	250	3	-	3	-	-	=	=	-1.5	3	3	n	-	я	=	n	40	3	3	3	-	=	n	3	100	3		-	3	3	3	3	
Ţ	Min																																						
	Meas.	ם פ	1	27	37	4≺	17	7	27	27	37	37	4Υ	4≺	14	18	2A	2B	3A	3B	44	4B	14	18	2A	2B	3A	3B	44	4B	14	18	2A	2B	3A	3B	44	4B	
4	41	V _{cc}	4.5 V	-	=		=	=	=	=	=	=	=	-		=	-	=	=	=	=	=	5.5 V	=	=	=	=	=	=	=	=	=	=	=	=	-	=	=	
13	13	4B	5.5 V			2.0 V	5.5 V		-	-			2.0 V	0.8 V								-12 mA	GND				-	-	-	2.4 V	GND		-					5.5 V	
12	12	44	5.5 V	-	=	2.0 V	5.5 V	=	=	=	=		0.8 V	2.0 V							-12 mA		GND	=	=	=	=		2.4 V	GND	=	=	=	=	=		5.5 V	GND	
7	11	4				16 mA							15.0 V	15.0 V	=																=								=
10	10	3B	5.5 V	5.5 V	2.0 V	5.5 V			-	-	2.0 V	0.8 V	5.5 V	5.5 V						-12 mA			GND				-	2.4 V	GND				-			5.5 V	GND	GND	
6	6	3A	5.5 V	5.5 V	2.0 V	5.5 V		=	-	=	0.8 V	2.0 V	5.5 V	5.5 V					-12 mA				GND			=	2.4 V	GND	-			=	=	=	5.5 V	GND			
80	8	37			16 mA						15.0 V	15.0 V																											
7	7	GND	GND		-			=	-				=	=	=	=	=			=			=					-	-	=		-	-		=		=		
9	9	2Y		16 mA					15.0 V	15.0 V																			=								-		
2	5	2B	5.5 V	2.0 V	5.5 V	=		=	2.0 V	0.8 V	5.5 V	=	=	=				-12 mA					GND	=	=	2.4 V	GND	=	=	=		=	=	5.5 V	GND	=	=	=	
4	4	ZA	5.5 V	2.0 V	5.5 V		=	=	0.8 \	2.0 V	5.5 V						-12 mA						GND	GND	2.4 V	GND							5.5 V	GND					
ဗ	3	1	16 mA				15.0 V	15.0 V	=						=	=	=													=		-	=	=	=			=	=
2	2	1B	2.0 V	5.5 V	-		2.0 V	0.8 V	5.5 V		-			=		-12 mA							GND	2.4 V	GND			=	-			5.5 V	GND						
-	1	14	2.0 V	5.5 V		=	V 8.0	2.0 V	5.5 V	=	=	=	=	=	-12 mA								2.4 V	GND	=	=	=	=	=	=	2.5 V	GND	=	=	=	=	=	=	
Cases A,B,D	Case C	Test No.	-	2	ဗ	4	2	9	7	œ	6	10		12	13	4	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	
	MIL- STD-883	method	3007	я	я	я																	3010	=		=	-	2	=	=	3010	=	-	21	=		=		
	Symbol		Vol2		n	n	ICEX	, ,		n	=	23	3	3	VIC	, 3	3	n	=	n	=	73	IH1	n	73	3	=	=	n	2	l _{IH2}	n n	=	=	3	3	2	73	
	Clibrorous	dnoifianc	-	T _C = +25°C	n	n	×		n	,,	я	я	я	3	3	я	n	3	3	n	n	n	3	n	n	я	3	3	3	n	3	я	n	я	я	3	n	n	

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TABLE III. Group A inspection for device type 05. - Continued Terminal conditions (High ≥ 2.0 V or Low ≤ 0.8 V or open).

	ţ	<u> </u>	mA	z z	3	"	n	n	,,	3	n				ns	3	ÿ	3	_	3	,	ű	_	7	,,	×	_	n	,,	3	
imits											~								0												
Test limits	Max		-1.6	-	-	-	-	-	-	-	22	∞			25	3	3	n	30	3	3	3	35	3	3	"	40	3	3	3	
	Min		<i>L</i> '-	-	=	=	-	-	-	=					3	=	-	-	=	=	=	•	-	-	=	-	=	-	=	-	
	Meas.		1A	18	2A	2B	3A	3B	44	4B	Vcc	V _{CC}			1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	1A to 1Y	2A to 2Y	3A to 3Y	4A to 4Y	
14	14	Vcc	5.5 V	-	=	-	=	=	-	=	=	=			5.0 V	=	=	-	=	-	-	-	=	=	=	-	=	-	=	-	
13	13	4B	5.5 V	-	=	-	-	-	-	0.4 V	5.5 V	GND						2.4 V				2.4 V				2.4 V				2.4 V	
12	12	44	2.5 V		=	=	=		0.4 V	5.5 V	5.5 V	GND						Z				Z				Z				Z	
11	11	44									=							OUT				DUT				OUT				OUT	
10	10	3B	5.5 V	-	-	=	-	0.4 V	5.5 V	=		GND	or ICEX.				2.4 V				2.4 V				2.4 V				2.4 V		
6	6	3A	5.5 V		=	=	0.4 V	5.5 V		-			125° C and V _{IC} tests are omitted. $V_{IL} = 0.7 \text{ V for ICEX}$				Z				Z				Z				Z		
8	8	37											iitted. Vil	tted.			OUT				OUT				OUT				OUT		
7	7	GND	GND	=	=			=	=	=	=	=	its are om	s are omi	GND	=	=	=	=	=	=	=	=	=	=			=	=	=	
9	9	2Y							=				nd V _{IC} tes	d V _{IC} test		DOLT				OUT				OUT				OUT			
5	5	2B	5.5 V	=	=	0.4 V	5.5 V	=	=		=	GND	125° C a	-55° C an		2.4 V				2.4 V				2.4 V				2.4 V			ر قو
4	4	2A	5.5 V	5.5 V	0.4 V	5.5 V						GND	cept T _C =	p 1, except T _C = -55° C and V _{IC} tests are omitted		Z				Z				Z				Z			- CT +000
3	3	17								-	=		oup 1, exc	oup 1, exc	OUT				OUT				OUT				OUT				0, 01,0
2	2	1B	5.5 V	0.4 V	5.5 V	=	=	=		-	=	GND	for subgro	for subgro	2.4 V				2.4 V				2.4 V				2.4 V				for only or
1	1	14	0.4 V	5.5 V	=		=	=		=		GND	l limits as	l limits as	Z				N				Z				NI				oc oficeil
Cases A,B,D	Case C	Test No.	37	38	39	40	14	42	43	44	45	46	Same tests, terminal conditions and limits as for subgroup 1, except T _C =	Same tests, terminal conditions and limits as for subgrou	47	48	49	20	51	52	53	54	55	56	22	58	26	09	61	62	Same tests terminal conditions and limits as for subgroup 10 event To = 55°C
	MIL- STD-883	method	3009	я	а	3	а	а	а	я	3005	3005	sts, termina	sts, termina	3003	(Fig 5)	=						=		-		=	-	-		Caiman of
	odmy	5	11	n	n	3	n	×	=	7	ICCL	Іссн	Same te	Same te	tPHL	3	3	"	tPLH	ä	ä	3	tPHL	n	3	"	tPLH	3	3	ä	Como to
	Subdio	2 5 5 6 7 7	7	$T_{\rm C} = +25^{\circ}{\rm C}$	3	n	7	3	3	3	3	3	2	က	6	$T_{\rm C} = +25^{\circ}{\rm C}$	n	3	=	=	n	n	10	$T_{\rm C} = +125^{\circ}{\rm C}$	n	3	=	=	n	3	7

5. PACKAGING

5.1 <u>Packaging requirements.</u> For acquisition purposes, the packaging requirements shall be as specified in the contract or order (see 6.2). When packaging of materiel is to be performed by DoD or in-house contractor personnel, these personnel need to contact the responsible packaging activity to ascertain packaging requirements. Packaging requirements are maintained by the Inventory Control Point's packaging activity within the Military Service or Defense Agency, or within the military service's system command. Packaging data retrieval is available from the managing Military Department's or Defense Agency's automated packaging files, CD-ROM products, or by contacting the responsible packaging activity.

6. NOTES

(This section contains information of a general or explanatory nature that may be helpful, but is not mandatory)

- 6.1 <u>Intended use.</u> Microcircuits conforming to this specification are intended for logistic support of existing equipment.
 - 6.2 Acquisition requirements. Acquisition documents should specify the following:
 - a. Title, number, and date of the specification.
 - b. PIN and compliance identifier, if applicable (see 1.2).
 - c. Requirements for delivery of one copy of the conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
 - d. Requirement for certificate of compliance, if applicable.
 - e. Requirements for notification of change of product or process to acquiring activity in addition to notification to the qualifying activity, if applicable.
 - f. Requirements for failure analysis (including required test condition of method 5003), corrective action and reporting of results, if applicable.
 - g. Requirements for product assurance options.
 - h. Requirements for carriers, special lead lengths or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements will not apply to direct purchase by or direct shipment to the Government.
 - i. Requirements for "JAN" marking.
 - j. Packaging requirements (see 5.1).
- 6.3 <u>Qualification</u>. With respect to products requiring qualification, awards will be made only for products which are, at the time of award of contract, qualified for inclusion in Qualified Manufacturers List QML-38535 whether or not such products have actually been so listed by that date. The attention of the contractors is called to these requirements, and manufacturers are urged to arrange to have the products that they propose to offer to the Federal Government tested for qualification in order that they may be eligible to be awarded contracts or purchase orders for the products covered by this specification. Information pertaining to qualification of products may be obtained from DSCC-VQ, 3990 E. Broad Street, Columbus, Ohio 43123-1199.
- 6.4 <u>Superseding information</u>. The requirements of MIL-M-38510 have been superseded to take advantage of the available Qualified Manufacturer Listing (QML) system provided by MIL-PRF-38535. Previous references to MIL-M-38510 in this document have been replaced by appropriate references to MIL-PRF-38535. All technical requirements now consist of this specification and MIL-PRF-38535. The MIL-M-38510 specification sheet number and PIN have been retained to avoid adversely impacting existing government logistics systems and contractor's parts lists.

6.5 <u>Abbreviations, symbols and definitions.</u> The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331, and as follows:

GND	Ground zero voltage potential.
V _{IN}	
V_{IC}	Input clamp voltage.
I _{IN}	Current-flowing into an input terminal.

- 6.6 <u>Logistic support.</u> Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be acquired to device class B (see 1.2.2), lead material and finish A (see 3.4). Longer lead lengths and lead forming should not affect the part number.
- 6.7 <u>Substitutability.</u> The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-35810 device types and may have slight physical variations in relation to case size. The presence of this information should not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-PRF-38535.

Device type	Commercial type
01	5406
02	5416
03	5407
04	5417
05	5426

- 6.8 <u>Supersession information.</u> MIL-M-38510/8F supersedes MIL-M-38510/8E. MIL-M-0038510/8C(19) was issued as an "in lieu of" document for MIL-M-38510/8B and was superseded by MIL-M-38510/8D.
- 6.9 <u>Changes from previous issue</u>. The margins of this specification are marked with asterisks to indicate where changes from the previous issue were made. This was done as a convenience only and the Government assumes no liability whatsoever for any inaccuracies in these notations. Bidders and contractors are cautioned to evaluate the requirements of this document based on the entire content irrespective of the marginal notations and relationship to the last previous issue.

Custodians:

Army - CR

Navy - EC

Air Force - 11

DLA - CC

Preparing activity: DLA - CC

(Project 5962-2005-005)

Review activities:

Army - MI, SM

Navy - AS, CG, MC, SH, TD

Air Force - 03, 19, 99

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at http://assist.daps.dla.mil.